REGISTRATION REPORT

2010 Registration Chair: Deb Frincke

Here's the important part

We hit room capacity EARLY
The workshops are GROWING
Student participation is HIGH
Lots of CALIFORNIANS
More from the US GOVERNMENT and nat'l labs
We had a few problems with VOCANO ASH ...

... and Yvonne deserves a round of applause for her hard work.

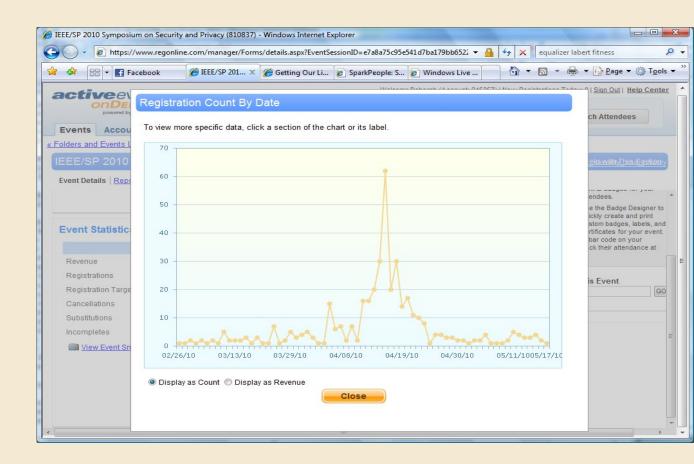
Registration By Year

Early vs. Late Registrations

In 2010, we hit our "just in case" capacity maximum of 320 two days after preregistation closed!

With extended cap: 91% early

Registrations by Date: 2009 and 2010



More about 2010

IEEE Members

Early: 92 Late:30

Life Members: 2 Non Members

Early: 64 Late: 28

Student Members

Early 93

Late 5

Student Nonmembers

Early 31 Late 4

Registration by Geographic Region

2009

Last year

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Asia 8 Canada 11 Europe 41 US 212

20 of these were just for gala

<footer> <date/time>

The Detailed look ... All events

Austria 5 Belgium 4 Canada 7 China 4 Denmark 1

Finland 2

France 3

Germany 4

Greece 1

Israel 1

·Italy 4

Japan 1

Korea Ren of

Korea, Rep of Tunisia 1Luxembourg 1United Kingdom

· Netherlands 37

· Saudi Arabia 1 California 133

United States(other) 208

Singapore 3

- Sweden 1

Switzerland 1

Taiwan 2

399 across all

Registrations by Sector

2009

2010

Government 15 Industry 45 Academia 93 Student 102 Other 17

<footer>SP 2010 Registration Report

Workshop Registrations: W2SP

Room Capacity Nearing Comfortable Limits

Additional Stats for WS2P and SNSP

Organizers

General Chair:s Larry Koved, Dan Wallach

Program Chair: Collin Jackson

Statistics

W2SP

- 12 papers accepted (6 full, 6 position)
- · 26 submitted

SNSP

· 1 full paper (out of 6) accepted for W2SP

Overall

13 out of 32 (41% acceptance rate)

Al accepted papers published on website

Workshop Registrations: SADFE

Room Capacity Nearing Limits at 45

SADFE Statistics

General Chair: Rob Erbacher

Program Chairs:

Barbara Endicott-Popovsky

Wenke Lee

Statistics

23 papers submitted

10 accepted

Acceptance rate 43%

Averate number of reviews/paper: 3

Papers published in hardcopy proceedings, IEEE Press